

Features

- Low forward voltage drop
- Low leakage current
- Moisture sensitivity: level 1, per J-STD-020
- Low profile, typical thickness 1.0mm



Package: eSGB(SMAF)

Applications

For uses in low voltage, high frequency inverters, free wheeling and polarity protection applications.

Maximum Ratings ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	LS545	Unit
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	45	V
Maximum RMS Voltage	V_{RMS}	31.5	V
Maximum DC Blockingg Voltage	V_{DC}	45	V
Maximum Average Forward Rectified Current	$I_{F(AV)}^1$	5.0	A
	$I_{F(AV)}^2$	3.0	
Peak Forward Surge Current (8.3 ms single half sine-wave superimposed on rated load)	I_{FSM}	150	A
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 to +125	°C

Electrical Characteristics ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Test Conditions	Symbol	Min	Typ	Max	Unit
Instantaneous Forward Voltage	$I_F=1\text{A}, T_J=25^\circ\text{C}$	V_F	-	0.35	-	V
	$I_F=2\text{A}, T_J=25^\circ\text{C}$		-	0.38	-	
	$I_F=3\text{A}, T_J=25^\circ\text{C}$		-	0.40	-	
	$I_F=5\text{A}, T_J=25^\circ\text{C}$		-	0.44	0.46	
	$I_F=3\text{A}, T_J=125^\circ\text{C}$		-	0.30	-	
	$I_F=5\text{A}, T_J=125^\circ\text{C}$		-	0.36	-	
Instantaneous Reverse Current	$V_R=36\text{V} T_A=25^\circ\text{C}$	I_R	-	39	-	μA
	$V_R=45\text{V} T_A=25^\circ\text{C}$		-	120	200	
	$V_R=45\text{V} T_A=125^\circ\text{C}$		-	38	60	mA
Typical Junction Capacitance	4.0 V, 1 MHz	C_J	300			pF
Typical Thermal Resistance	Junction to Mount	$R_{\theta JM}^1$	26			°C/W

Note 1) Mounted on PCB with 8.0x8.0mm copper pads, 2 OZ, FR4 PCB.

2) Mounted on recommended copper pad area, free air.

Ratings and Characteristics Curves ($T_A = 25^\circ C$ unless otherwise noted)

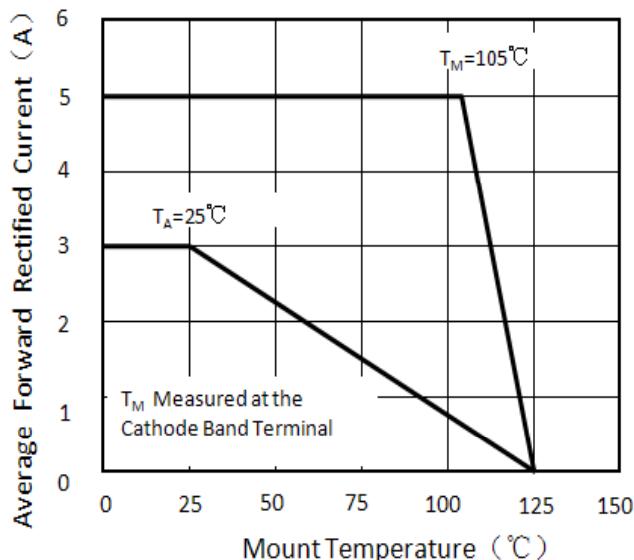


Figure 1. Forward Current Derating Curve

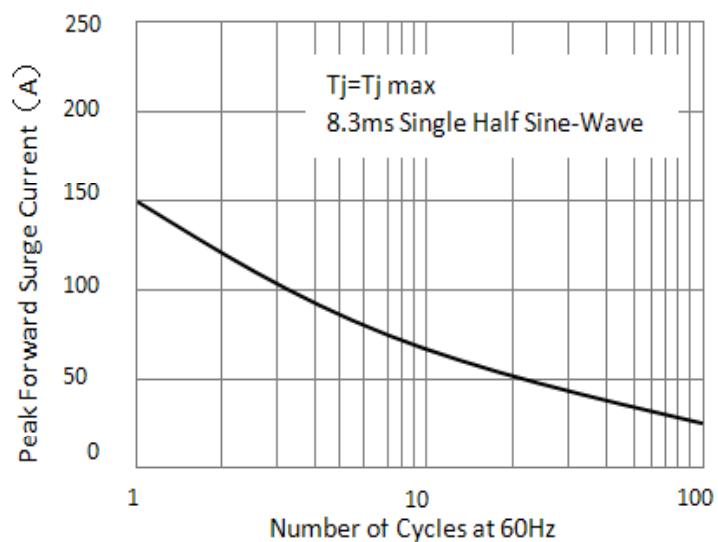


Figure 2. Maximum Non-Repetitive Peak Forward Surge Current

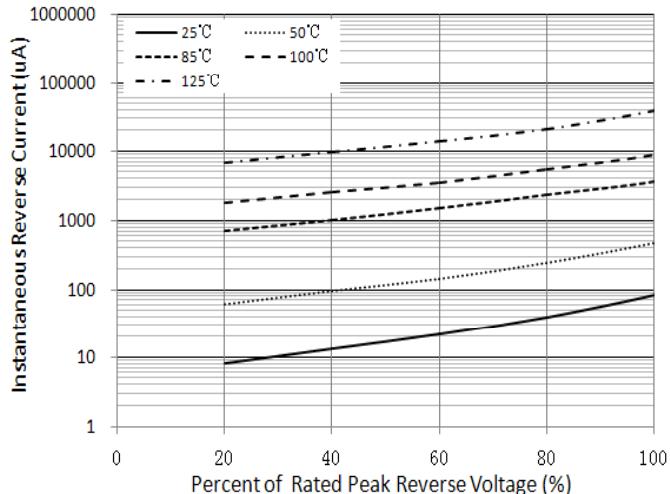


Figure 3. Typical Reverse Characteristics

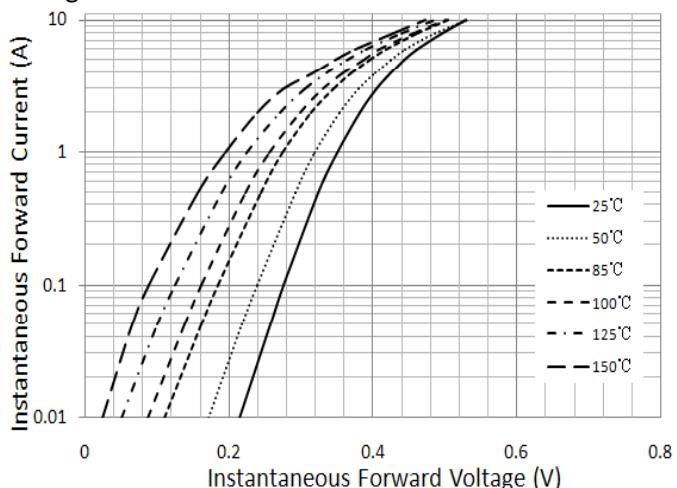


Figure 4. Typical Instantaneous Forward Characteristics

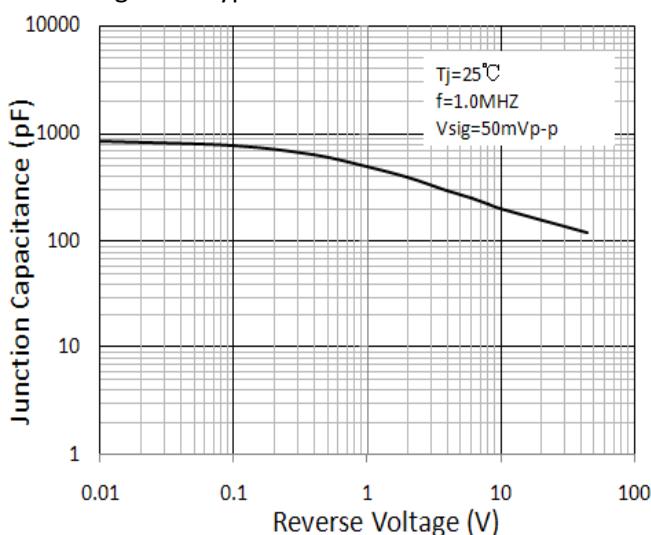
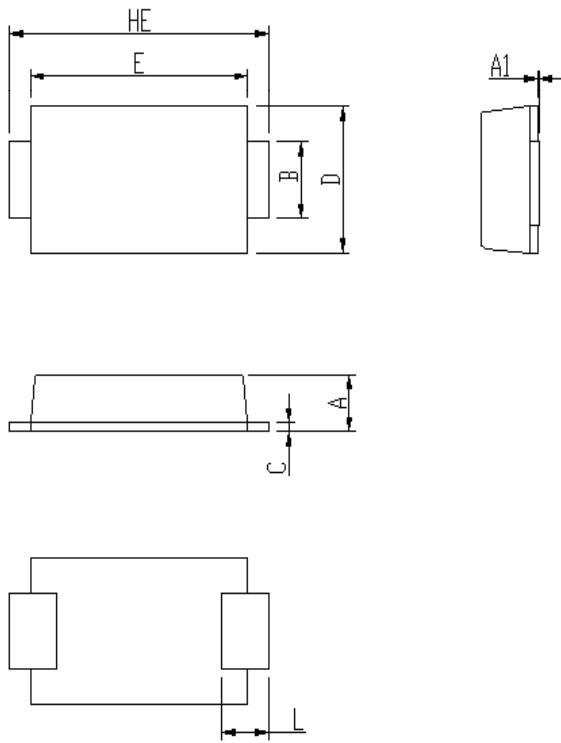


Figure 5. Typical Junction Capacitance

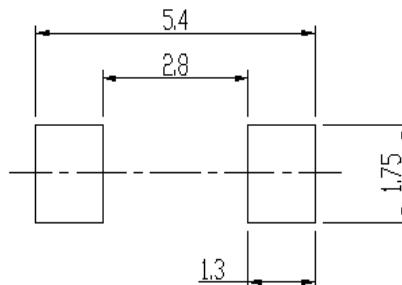
Package Outline Dimensions

eSGB (SMAF)



DIM	Unit: mm		Unit: inch	
	MIN	MAX	MIN	MAX
A	0.92	1.08	0.036	0.043
A1	0	0.1	0.000	0.004
B	1.25	1.45	0.049	0.057
C	0.1	0.25	0.004	0.010
D	2.6	2.8	0.102	0.110
E	4.1	4.3	0.161	0.169
L	0.7	1.1	0.028	0.043
HE	4.8	5.2	0.189	0.205

Soldering footprint



Packing Information

Packing quantities

3000 pcs/Reel , 12mm Tape, 13" Reel

Tape & Reel Specification

